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# TABLE OF CONTENTS

## Power Integrity

Design of On-Chip Linear Regulator Module And Measurement of Power Distribution	
Network Noise Fluctuation at High-Speed Output Buffer .....	3
Interconnected Capacitors for Effective Power Delivery Noise Suppression Across Domains.....	7
Modeling of Power Distribution Networks for Path Finding .....	11

## Advanced Simulation Techniques

Statistical Analysis via Generalized Decoupled Polynomial Chaos.....	17
A Stabilized Leapfrog Scheme for Circuit-Based Analysis of Power Delivery Network.....	21
Enhanced Macromodels of High-speed Low-Power Differential Drivers .....	25
Application of CMA Evolution Strategy to Synthesis of Multi-resonance SPICE Models up to 20 GHz.....	29

## Electromagnetics

On the Low Frequency Theory of Characteristic Mode .....	35
Hierarchical Modeling and Scalable Algorithms for In-Situ Analysis of Integrated Circuit Packages.....	39
Evaluation of Near-singular Integrals for Quadrilateral Basis in Integral Equation Solver .....	43
An electromagnetic model for back-drilled vias.....	47

## High-Speed Links

Automated Frequency Selection for Machine-Learning based EH/EW prediction from S-Parameters .....	53
High-Speed Serial Link Challenges using Multi-Level Signaling .....	57

## Student Software Demonstration

Intelligent Rapid Investigation of S-parameters (IRIS).....	63
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## Poster Session And Industry Reception

The Effect of Temperature on Performance of a RF CMOS Power Amplifier and Bond Wires .....	69
IBIS-AMI Modelling of High-Speed Memory Interfaces .....	73
Prediction of Near-Field Shielding Effectiveness for Conformally-shielded SiP using a Magnetic Probe .....	77

New Broadband Equalizer Optimization Technique for Digital System Designs.....	81
Novel De-embedding Method with Look-Up Table for Characterization of Interconnects.....	85
A Prediction Method of Heat Generation in the Silicon Substrate for 3-D ICs .....	89
An Electrical Study of USB2.0 Channels Supporting Multiplexers/BC1.2 Power Switches/Charging Modules .....	93
Global Sensitivity Based Dimension Reduction for Fast Variability Analysis of Nonlinear Circuits.....	97
Numerical Modeling of Electromagnetic Interference (EMI) and Radiation Problems for Large Multiscale Structures .....	101
Signal Integrity for USB 3.1 Gen 2 Front End Challenging Loss Budget.....	105
Modeling and Measurement of High-bandwidth and High-density Silicone Rubber Socket for 100Gbps Transceiver IC Test.....	109
Efficient Methodology for Modeling Structure of High-Speed Long Transmission Lines.....	113
Reduction of PDN Induced Coupling into Signal Lines Using PTL Power Distribution .....	117

## **Electromagnetics II**

A 2D-FDFD with Integrated Via Model for Accurate Simulation of PCBs and Packages .....	123
PEEC Macromodels for Above Plane Decoupling Capacitors.....	127
A Study of Conductor Modeling Using the Surface Integral Equation .....	131
Novel Time Domain Integral Equation Method Hybridized with the Macromodels of Circuits .....	135

## **RF Modeling and Design Techniques**

Process Robustness and Reproducibility of sub-mm Wave Flip-Chip Interconnect Assembly..	141
Design and Signal Integrity Analysis of High Bandwidth Memory (HBM) Interposer in 2.5D Terabyte/s Bandwidth Graphics Module .....	145
Performance Modeling and Optimization for On-Chip Interconnects in Memory Arrays.....	149

## **Advanced Packaging Technologies and Techniques**

Broadband material model identification with GMS-parameters .....	155
Impact of Fiber Weaves on 56 Gbps SerDes Interface in Glass Epoxy Packages .....	159
Timing Skew Enabler Induced by Fiber Weave Effect in High Speed HDMI Channel by Angle Routing Technique in 3DFEM.....	163
Trace mis-registration margin on PCB: How much is enough .....	167
A Novel 3-D Printed Loop Antenna Using Flexible NinjaFlex Material for Wearable and IoT Applications .....	171

## **Advanced Macromodeling and Simulation for SI/PI**

Fast Singular-Value Decomposition of Loewner Matrices for State-space Macromodeling .....	177
Stability Preserving Algorithm for Model Order Reduction of Active Networks.....	181
Fast Model Order Reduction of RC Networks with Very Large Order and Port Count .....	185
MOS Models for LIM Transient Simulations.....	189

## **Advances in High-Speed Channel Characterization**

Voltage and Time Margin Analysis for Wireline Links in High Dimensional Design Spaces ...	195
Accurate Statistical Analysis of High-Speed Links with PAM-4 Modulation .....	199
Return Loss Characterization and Analysis of High-Speed Serial Interface .....	203

## **High-Speed Link Design**

Crosstalk Reduction by Matrix Matching.....	209
36-GHz-Bandwidth Quad-channel Driver Module using Compact QFN Package for Optical Coherent Systems.....	213
Analysis and System Optimization of High Performance Clocking for Modern Mobile Platforms .....	217
Challenges of High-Speed Channel Design on GPU Accelerated System.....	221
Delay Estimation Using SVD-Based Causal Fourier Continuations for High Speed Interconnects .....	225

<b>Author Index .....</b>	<b>229</b>
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